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THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. 09/148,723
Priority Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Priority Group Art Unit 3729
Priority Examiner D. Tugbang
Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

(see in paper #3)

RESPONSE TO MAY 22, 2000 OFFICE ACTION
PRELIMINARY AMENDMENT TO ACCOMPANY CPA FILING

Suppl

To: BOX CPA
Assistant Commissioner for Patents
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)
Wells, St. John, Roberts, Gregory & Matkin P.S.
601 W. First Avenue, Suite 1300
Spokane, WA 99201-3817

Sir:

Responsive to the Final Office Action dated May 22, 2000,
Applicant amends and remarks as follows [unless otherwise indicated,
deletions are bracketed, additions are underlined]:

AMENDMENTS

In the Claims